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(19) **United States**(12) **Patent Application Publication****Wu et al.**(10) **Pub. No.: US 2022/0354007 A1**(43) **Pub. Date: Nov. 3, 2022**(54) **METALLIC HOUSING OF ELECTRONIC DEVICE**(71) Applicant: **HTC Corporation**, Taoyuan City (TW)(72) Inventors: **Tim Chung-Ting Wu**, Taoyuan City (TW); **Cheng-Chieh Chuang**, Taoyuan City (TW); **Chi-Jen Lu**, Taoyuan City (TW); **Chun-Lung Chu**, Taoyuan City (TW); **Chien-Hung Lin**, Taoyuan City (TW)(73) Assignee: **HTC Corporation**, Taoyuan City (TW)(21) Appl. No.: **17/866,535**(22) Filed: **Jul. 17, 2022****Related U.S. Application Data**

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(57)

ABSTRACT

A method of manufacturing a casing of an electronic device including the following steps is provided. A metallic housing is provided, wherein the metallic housing has an inner surface and an outer surface opposite to the inner surface and includes a back region and at least one side region. At least one gap, a plurality of apertures and a non-conductive layer are formed on the inner surface of the metallic housing, wherein the apertures is formed on a surface of the at least one gap, part of the non-conductive layer is formed in the at least one gap and extended from the back region to the at least one side region, and part of the non-conductive layer is extended into the apertures. Part of the metallic housing is removed for exposing part of the non-conductive layer, thereby forming a plurality of non-conductive spacers located in the at least one gap.

